Materials Declaration

Package	LFCSP
Body Size	7 X 7
LeadCount	48
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	85	4.25 E-02	336123
Epoxy Resin	10	4.99 E-03	39544
Phenol Resin	5	2.50 E-03	19772
Subtotal		4.99 E-02	395439

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	6.50 E-02	514996
Fe	2.35	1.57 E-03	12413
Zn	0.12	8.01 E-05	634
P	0.03	2.00 E-05	158
Subtotal		6.67 E-02	528201

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.35 E-03	10685

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	3.34 E-04	2644

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.00 E-03	7918

Chip

	% of Chip	Weight (g)	PPM
Si	100	5.97 E-03	47254

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75	7.44 E-04	5894
Resin	25	2.48 E-04	1965
Subtotal		9.92 E-04	7858

Package Totals

Weight (g)	PPM
1.26 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES.
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES.
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cr+6	3	EPA Method 3060A & 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

Materials Declaration

Package	LFCSP
Body Size	7 X 7
LeadCount	48
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
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Epoxy Resin	10	4.99 E-03	39544
Phenol Resin	5	2.50 E-03	19772
Subtotal		4.99 E-02	395439

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Fe	2.35	1.57 E-03	12413
Zn	0.12	8.01 E-05	634
P	0.03	2.00 E-05	158
Subtotal		6.67 E-02	528201

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.35 E-03	10685

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	2.84 E-04	2247
Pb	15	5.01 E-05	397
Subtotal		3.34 E-04	2644

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.00 E-03	7918

Chip

	% of Chip	Weight (g)	PPM
Si	100	5.97 E-03	47254

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75	7.44 E-04	5894
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Die Attach Paste

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ANALOG DEVICES

ADI Proprietary